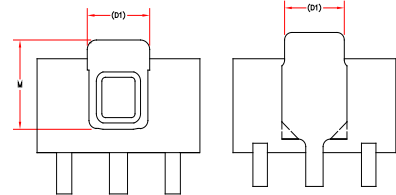
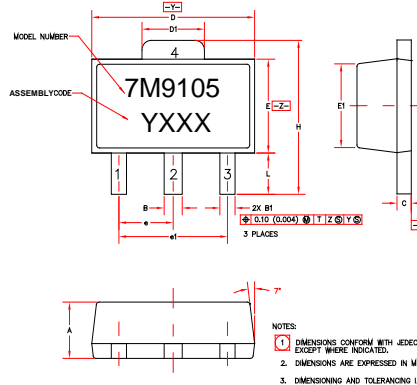


Mechanical Information

Package Marking and Dimensions

Marking: Part number – 7M9105
 Assembly code - YXXX

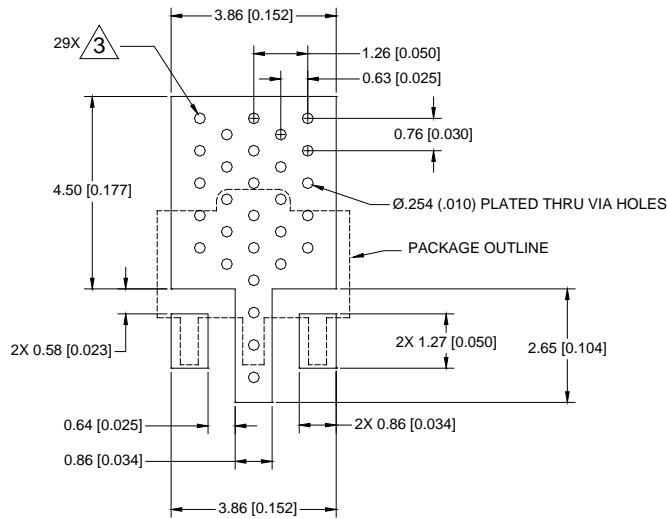


Alternate Backside Patterns
 (May be supplied with either pattern shown)

SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX
A	1.40 (.055)	1.50 (.059)	1.60 (.063)	E	2.29 (.090)	2.50 (.099)	2.60 (.103)
B	.44 (.017)	.50 (.020)	.56 (.022)	E1	2.13 (.084)	2.20 (.087)	2.29 (.090)
B1	.36 (.014)	.45 (.018)	.46 (.019)	*	1.50 BSC (.059)	3.00 BSC (.118)	
C	.35 (.014)	.40 (.016)	.44 (.017)	H	3.94 (.155)	4.10 (.161)	4.28 (.167)
D	4.40 (.173)	4.50 (.177)	4.60 (.181)	L	.89 (.035)	1.10 (.043)	1.20 (.047)
D1	1.62 (.064)	1.75 (.069)	1.83 (.072)	M	2.1 (.087)	2.40 (.095)	2.4 (.100)

NOTES:
 1. DIMENSIONS CONFORM WITH JEDEC TO-243C EXCEPT WHERE INDICATED.
 2. DIMENSIONS ARE EXPRESSED IN MM (INCHES).
 3. DIMENSIONING AND TOLERANCING IAW ANSI Y14.5M

PCB Mounting Pattern



NOTES:

1. The pad pattern shown has been developed and tested for optimized assembly at TriQuint Semiconductor. The PCB land pattern has been developed to accommodate lead and package tolerances. Since surface mount processes vary from supplier to supplier, careful process development is recommended.
2. All dimensions are in millimeters [inches]. Angles are in degrees.
3. Use 1 oz. copper minimum for top and bottom layer metal.
4. Vias are required under the backside paddle of this device for proper RF/DC grounding and thermal dissipation. We recommend a 0.35mm (#80/.0135") diameter bit for drilling via holes and a final plated thru diameter of 0.25mm (0.10").
5. Ensure good package backside paddle solder attach for reliable operation and best electrical performance.
6. Place mounting screws near the part to fasten a back side heat sink.
7. Do not apply solder mask to the back side of the PC board in the heat sink contact region.
8. Ensure that the backside via region makes good physical contact with the heat sink.